Nonintrusive and Adaptive Monitoring for Locating Voltage Attacks in Virtualized FPGAs

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With every new generation, high-end FPGAs are becoming richer in features and resources, making the usage model of single-user per FPGA decreasingly cost-efficient. Although virtualized FPGAs enable multiple users to share the same FPGA, this multi-tenancy is not employed in practice because of potential security threats, such as voltage attacks. These attacks use power-wasting circuits to exercise excessive switching activity on the target FPGA to cause extreme voltage fluctuations, which produce timing faults in collocated circuits or, in extreme cases, reset target FPGA. In this work, we present the idea of automated embedding of the on-chip voltage sensors into the virtualized FPGAs and continuous monitoring of the core voltage for suspected fluctuations caused by a voltage attacker. Our sensors are nonintrusive and placement-adaptive because we implement them immediately after placing and routing the user design with resources that are left unused. We devise a novel measurement technique to continuously analyze the sensor outputs and locate the power-wasting circuits. Additionally, we are the first to use a synchronous power-wasting attacker, capable of producing timing faults, on Xilinx 7-series FPGAs and to successfully locate it. Hence, our proposed monitoring system enables the virtualized FPGA to identify the voltage attackers, at minimal cost, and prevent them from repeating the attack.

I. INTRODUCTION

Each new generation of high-end FPGAs is richer than the previous in terms of programmable resources, routing, embedded memories, and versatile hardened modules. The traditional usage model of the FPGA assumes a single user having the control over all the FPGA resources, but with the current trend of enlarging FPGAs, soon, this model will be replaced with multi-tenant virtualized FPGA to avoid hardware underutilization [1]. Virtualized FPGAs let multiple users run their circuits (also known as roles) on the same FPGA. In the virtualized setting, a part of the FPGA is reserved for the shell, which handles the resource management and sharing [2], [3].

The main obstacles in the way of deployment of virtualized FPGAs are new security threats [4]. Interactions between different roles, distrusted outsiders as well as malicious insiders, may violate data confidentiality, the correctness of execution, or even the availability of services in the colocated roles [5]–[7]. Voltage attacks are among the most effective and concrete security threats of virtualized FPGAs [8]–[14]. A voltage attacker uses power-wasting circuits to overaggressively exercise switching activity to drop the core supply voltage and cause timing failures in the colocated roles (timing fault injection) or, in the extreme case, reset the whole FPGA (denial-of-service attack).

Many industrial FPGAs benefit from embedded sensors and detect sudden increases in the temperature and voltage with high resolution ($\pm 4^\circ\text{C}$ max error for temperature and $1\%$ max error for voltage, respectively [15]). However, these sensors have limited spatial resolution [16]. Each FPGA contains only a single embedded voltage sensor for monitoring the core voltage and a single embedded temperature sensor for monitoring the FPGA temperature. In the case of a voltage attack, these embedded sensors can detect the attack but cannot be used to locate the source of it and ban the malicious role.

A network of on-chip voltage sensors would provide sufficient spatial resolution to locate the source of voltage attack at the cost of reserving some of the programmable logic and routing resources inside the role for implementing these sensors [9]. In this work, we improve this approach by proposing nonintrusive and adaptive on-chip voltage sensors. Our approach does not reserve any resources and instead utilizes the programming logic and routing resources that are left unused inside each role. The feasibility requirement of our approach is exceptionally lightweight: a single free configurable logic block (CLB) inside each clock region (CR). We move all the logic required to read and understand the sensor outputs from the user space to the shell, which already contains all the management logic. We minimize the sensor intrusion and constraints on the user by introducing a new design step immediately after the placement and routing, to embed the sensors adaptively into the role. Our design flow is fully automated and entirely compatible with the design flow employed by cloud FPGA providers (e.g., Amazon AWS [39]).

The main contributions of our work are the following:

- Nonintrusive sensing: minimized use of the FPGA logic resources for the implementation of the network of sensors (12 eight-stage sensors versus 40 19-stage sensors in the state of the art [9]) with no constraints on the role.
- Adaptive sensing: placement-adaptive embedding of sensors into the design after it has been placed and routed.
- A novel measurement technique for spatially-distributed voltage sensors that can be used to reliably locate the voltage attackers.

In our experiments, we successfully embed the sensors into two variants of the power-wasting and the power-hungry cir-
A shell abstracts away the details of external peripherals (such as network, memory, and PCIe), contains their controllers, arbitrates external IO bandwidth between different roles, and keeps track of the presence of the roles on the FPGA. Several recent works propose to extend the shell with security features such as memory and network access isolation and data encryption [3], [17], [18]. Various schemes for partitioning the FPGA between the role space and the shell exist [2], [3], [17], [18]. Yazdanshenas et al. [3] propose to reserve the central clock regions for the shell and split the remaining space equally among four roles; this is illustrated in Fig. 1 on an example FPGA with 14 CRs. We follow the same partitioning scheme.

B. On-Chip Voltage Sensing

On-chip voltage sensors can be built on a modern FPGA using its programming logic and routing resources. Process, voltage, and temperature (PVT) variations affect the delay of the sensor elements and, consequently, the sensor output. There are two main on-chip sensor designs: time-to-digital converters (TDCs) and ring oscillators (ROs).

TDC consists of a chain of buffers whose input is connected to a reference clock. The outputs of all buffers are captured in a register, driven by a clock signal of the same frequency (but a different phase) as the reference clock. The register thus captures the propagation delay of the reference clock. To implement TDCs on FPGAs, one can use the carry chain primitives such as Xilinx CARRY4 [19]–[21].

RO-based sensors consist of a ring oscillator that feeds a frequency counter [22]. The counter is read every sampling period and the RO frequency, $f_{RO}$, equals

$$f_{RO} = \frac{\text{pulse count} + \text{truncation error}}{\text{sampling period}},$$

where the truncation error is associated with the partial clock pulse at the end of the sampling period. The RO frequency depends on the sensor design and the delay of the elements in the RO (buffers, latches, or flip-flops). Several previous works have experimentally and theoretically proved that there is an approximate linear relation between the FPGA supply voltage and the frequency of the RO-based sensors [7], [9], [23].

Even though the TDCs can capture voltage fluctuations with high resolution (in nanoseconds), they do not comply with the requirements of a nonintrusive adaptive voltage-monitoring setting for several reasons. The placement and routing of a TDC need frequent and careful online calibration [24]. For accuracy, TDCs require special resources, such as carry chains. In addition, they need several flip-flops and a priority encoder to convert the output to a binary value. Gnad et al. performed an experimental analysis of transient voltage fluctuations in a Xilinx Virtex-6 FPGA using TDCs and reported the resources utilization of these sensors as 214 flip-flops and 147 LUTs [25].

C. Voltage Attacker

As a result of their switching activity, FPGA circuits draw current from the power distribution network (PDN) and pro-
Enable
Enable
C
1
CLR
CE
D Q
FDCE
(a) (b)

![Diagram of two power-wasting circuits](image)

**Fig. 2. Two power-wasting circuits: (a) asynchronous [26] and (b) synchronous [29].**

Enable RO-based sensors to measure delay, variations in voltage and temperature [34], [35]. Zick et al. and Conn Jr. patented the procedure and methods of measuring frequency changes in ROs and translating it to variations in voltage and temperature [22]. Krishnamoorthy et al. and Conn Jr. take a different approach; they develop a tool (FPGADefender [41]) to automatically inspect the FPGA bitstreams for the presence of circuits that could be used in a malicious way [8], [31]. Unfortunately, such tools are not the ultimate solution as they can be tricked by normal circuits transforming into voltage attackers [42].

**IV. NONINTRUSIVE ADAPTIVE SENSORS**

To implement spatially-distributed sensors, one needs spatially-distributed resources. In previous works, it was common to reserve resources for implementing sensors on different parts of the FPGA [9], [25], [36]. While possible, doing this enforces tight constraints to the user for design placement, and violates the desired isolation between the role space and the shell [44]. In this section, we present our sensor design and the methodology for inserting our sensors in a nonintrusive way while adapting their placement to the user designs.

**A. Proposed On-Chip Sensors**

Design parameters that affect the RO-based sensor frequency include the number, functionality (inverting or not), and placement of its stages. Increasing the number of stages decreases the average RO frequency, but also reduces its standard deviation [45]. The placement of stages is important because the delays of the wires connecting the stages contribute to the RO frequency. To keep the wire delay minimal, it is desirable to fit all the stages into small programmable units (SLICE or CLB).

In this work, we opt for eight-stage ROs, which can fit inside a single CLB of 7-series Xilinx FPGAs, and we configure only one of the RO stages as inverting [45]. To keep the temperature impact minimal, we do not use any latches inside the RO [36]. And, we place the frequency counters inside the shell (outside of the user space). Table I gives the details of our RO-based sensor implementation and Fig. 1 illustrates the sensors embedded into a virtualized FPGA.

**B. Nonintrusive Sensor Insertion**

For the best design performance, no unnecessary placement or routing constraints should be imposed by the shell. Therefore, the voltage sensors should ideally (i) be implemented
after the user design is successfully placed and routed and (ii) use only the free (unused) resources. To that purpose, we add an intermediate step to the standard FPGA design flow. Fig. 3 illustrates the final fully-automated design flow.

1) Vivado Preprocessing: This first step is entirely standard. Here, the role is synthesized, placed and routed, and the design checkpoint (DCP) is saved.

2) RapidWright: The second step is where we update the DCP by inserting the sensors into the already placed and routed user design. We are able to automate this step only thanks to the the availability of RapidWright, an open-source platform from Xilinx Research Labs with a gateway to backend tools in Vivado [46]. So far, post-implementation debug insertion has been the most popular use case for RapidWright [47]. However, we show in this work that RapidWright can also be used to address FPGA security issues.

We use the JavaAPI interface of RapidWright to, firstly, read all the CLBs in the user design and cluster them by their corresponding CRs. Then, for each CR, we compute the boundaries of the minimum bounding box covering all the used CLBs. Inside those boundaries is where we search for the optimal CLB to insert the sensor (the algorithm describing the exact procedure is presented in Section IV-C). Finally, once the location for the sensor placement is chosen, we use RapidWright again to modify the DCP by adding the sensor resources and connections among them.

3) Vivado Postprocessing: This last step is, again, entirely standard. We feed the updated design checkpoint back to Vivado, to resume the standard design flow by routing the connections between the RO stages and connecting the RO outputs to the frequency counters inside the shell. Finally, the integrity checks are performed and the partial bitstream is generated.

C. Adaptive Placement

In this work, without loss of generality, we limit the number of sensors to the number of CRs inside the role region, and insert only one sensor into each CR. To maximize the impact of voltage fluctuations in the role region on the sensor frequency, we search for a free CLB, into which to embed the sensor, starting from the center of the minimum bounding box enclosing all the used CLBs in the target CR.

To insert the sensors, we first import the DCP file of the user design into RapidWright, which we use to read all the CLBs in the role regions assigned to the user (Fig. 3). RapidWright labels CLBs with several tags, of which the coordinates and occupancy are of our interest. We use this information along with the boundaries of CRs (publicly available in the FPGA datasheets) to divide the CLBs into groups corresponding to their CRs.

Algorithm 1 explains the next step, in which we decide in which unused CLB to place the sensor. Firstly, we iterate over all the CRs, and for each CR, find the minimum bounding box enclosing all the used CLBs (function MinBoundBox). The center of this bounding box is the starting point for the search algorithm. The search returns the center CLB, if it is free; if not, the search space expands from a 1 × 1 CLB to a square of 3 × 3 CLBs (one CLB expansion to the right, left, top, and bottom) and we check if any of the CLBs in this expanded search space is free. For efficiency, each time we encounter one used CLB, we remove it from the search space. The search space expansion continues until a free CLB is found (if multiple candidates are available, we choose any of them), or until all the CR boundaries are reached. In the unlikely case that the user design does not contain a single free CLB, the operators offering virtualized FPGAs may want to increase the number of role regions assigned to the user or transfer the user to another FPGA with bigger role regions.

### TABLE I

<table>
<thead>
<tr>
<th>Sensor Specification</th>
<th></th>
</tr>
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<tbody>
<tr>
<td>Hardware resources</td>
<td>8 LUTs (Virtex-7)</td>
</tr>
<tr>
<td>Data size</td>
<td>9 bits</td>
</tr>
<tr>
<td>Inverting stages</td>
<td>One</td>
</tr>
<tr>
<td>Stage type</td>
<td>Buffers</td>
</tr>
<tr>
<td>Sampling period</td>
<td>1.28 µs</td>
</tr>
<tr>
<td>Resolution</td>
<td>Less than 1 part in 100</td>
</tr>
<tr>
<td>Average frequency</td>
<td>143.35 MHz</td>
</tr>
</tbody>
</table>
Algorithm 1: Function FindFreeCLB, which takes CLBs of the same clock region to find optimal free CLB

Input: Set $C = \{c_i\}, i = 1, .., |N|$ of CLBs in the CR
Output: A free CLB as the candidate
Variables: $x_{min}, y_{min}, x_{max}, y_{max}, x_{start},$ and $y_{start}$ as coordinates

Variables: Integer variable: $iteration, C_s$
Variables: Set $U = \{u_i\}, i = 1, .., |U|$ of used CLBs
Variables: Integer variable $MaxIterations$, which controls the rounds of the search

foreach $c_i \in C$ do
  if $IsUsed(c_i) = TRUE$ then
    $U.add(c_i)$
  else
    if $U = Empty$ then
      $(x_{min}, y_{min}, x_{max}, y_{max}) \gets GetCenter(CR)$
    else
      $(x_{min}, y_{min}, x_{max}, y_{max}) \gets MinBoundBox(U)$
    $x_{start} \gets \frac{x_{max} - x_{min}}{2}$
    $y_{start} \gets \frac{y_{max} - y_{min}}{2}$
    $C_s \gets 0$
    $iteration \gets 0$
  while $C_s = 0$ & $iteration < MaxIterations$ do
    foreach $c_i \in C$ do
      $x_{CLB} \gets GetXCoordinate(c_i)$
      $y_{CLB} \gets GetYCoordinate(c_i)$
      if $x_{start} - iteration < x_{CLB} < x_{start} + iteration$ then
        if $y_{start} - iteration < y_{CLB} < y_{start} + iteration$ then
          if $IsUsed(c_i) = False$ then
            Candidate $\gets c_i$
            $C_s \gets 1$
            break
          else
            $Remove(c_i)$
          end if
        end if
      end if
    end foreach
    $iteration \gets iteration + 1$
end while

V. DISTRIBUTED VOLTAGE SENSING

While distributed on-chip sensors can monitor the voltage fluctuations in different parts of the FPGA to locate power-wasting circuits, collecting and comparing the frequency output of these sensors is not trivial, and we need a proper measurement metric and technique to understand the sensor outputs and draw conclusions.

A. Metric

As the supply line impedance varies from one region to another region on IC [34] and considering the variable placement of the proposed sensors, we aim at a metric that is resilient to sensor location. To devise it, let us start by looking at the relationship between the sensor frequency and the supply voltage [7], [9], [23], which can be modeled as

$$f(x, y, t) = k(x, y) \cdot V(x, y, t) + f_O(x, y).$$

Here, $V(x, y, t)$ is the supply voltage at time $t$ and at the location $(x, y)$ of the FPGA. Parameters that affect the location-dependent offset $f_O(x, y)$ and slope $k(x, y)$ are the RO design and the process and temperature variations [7]. To reduce the impact of RO design, we use an identical and very compact implementation for all the sensors (described in Section IV-A). To improve the resilience to temperature changes, we do not use any latches in the sensor design [19].

Let us now assume that we collect the frequency outputs of sensors $s_i$ and $s_j$, located at coordinates $(x_i, y_i)$ and $(x_j, y_j)$, respectively. Comparing their frequencies at time instant $t$, we obtain

$$\frac{f(x_i, y_i, t)}{f(x_j, y_j, t)} = \frac{k(x_i, y_i) \cdot V(x_i, y_i, t) + f_O(x_i, y_i)}{k(x_j, y_j) \cdot V(x_j, y_j, t) + f_O(x_j, y_j)}.$$ (3)

If coefficients $k$ and $f_O$ were location independent, it would be possible to derive a relationship between supply voltages at two different locations by observing the frequency output of two sensors and by using the above relation. However, that is not the case.

The extent at which $k(x, y)$ and $f_O(x, y)$ vary with the sensor location can be found experimentally. To that effect, we perform an extensive set of experiments, which show that $f_O(x, y)$ is far more location-dependent than $k(x, y)$ (these experiments are discussed in detail in Section VI-A). Therefore, for a metric to be as resilient to variable sensor location as possible, it must not contain the highly-variable offset $f_O(x, y)$.

Let us now compute the deviation of sensor frequency from its average value:

$$\Delta \tilde{f}(x_i, y_i, t) = f(x_i, y_i, t) - f_{avg}(x_i, y_i, t) = k(x_i, y_i) \cdot (V(x_i, y_i, t) - V_{avg}(x_i, y_i, t)) = k(x_i, y_i) \cdot \Delta V(x_i, y_i, t).$$ (4)

Comparing $\Delta \tilde{f}$ for two spatially-distant sensors gives:

$$\frac{\Delta \tilde{V}(x_i, y_i, t)}{\Delta \tilde{V}(x_j, y_j, t)} = \frac{\Delta \tilde{f}(x_i, y_i, t)}{\Delta \tilde{f}(x_j, y_j, t)} \cdot \frac{k(x_j, y_j)}{k(x_i, y_i)}.\text{ (5)}$$

This expression does not depend on the highly-variable factor $f_O$. Additionally, it shows that the relationship between voltage variations at different locations can be inferred by measuring and comparing the change in sensor frequency caused by those variations, provided that the coefficients $k$ depend minimally on the sensor location. We experimentally confirm that the latter holds (Section VI-A).

Therefore, we use $\Delta \tilde{f}(x_i, y_i, t)$ as our metric for comparing the transient voltage fluctuations at different sensor locations. In the next section we describe how we compute it.

B. Measurement Technique

In voltage attacks, the magnitude of voltage drop is significant, but the duration of this drop is as short as 10 µs [9], [11]. To locate such an attack, we need (i) to read continuously the sensor outputs and (ii) to choose a sampling period that
Fig. 4. We use two types of measurement windows: a sliding window of length \( L \) to measure the impact of transient voltage on sensor frequency, \( f(x, y, t) \), and an extending window to find the average frequency, \( f_{\text{avg}}(x, y, t) \).

allows the sensor outputs to be most affected by the transient voltage changes and not accumulate the voltage changes from different parts of the PDN.

To meet the requirements of transient voltage sensing, we devise a novel measurement technique which analyses the sensor outputs in two granularities: transient and steady-state windows. The choice of using these two types of windows is directly derived from the requirements of our metric \( \Delta f \).

Each window covers a set of samples, and its size is set based on the voltage change that should impact the window output. Fig. 4 illustrates these windows at two moments: \( i \) and \( i + 1 \) for a sliding transient window of size \( L \) and an extending steady-state window. The transient window reports the impact of transient voltage fluctuations on the sensor frequency, \( f(x, y, t) \) in Eq. (4). With each new sample, we report the worst-case (the lowest) recorded \( f(x, y, t) \) within the transient window. The steady-state window is used to compute the average sensor frequency \( f_{\text{avg}}(x, y, t) \) in Eq. (4).

There are general guidelines for setting the window size. The transient window size is set to the number of samples that cover the effective transient voltage drop (about 10 \( \mu \)s). The size of the steady-state window is not fixed; as we receive more sensor outputs, we increase the number of samples in it to improve the estimation of the average sensor frequency. To ease the online computation, one can limit the size of this window to a reasonably large number of samples.

VI. EXPERIMENTAL SETUP AND RESULTS

In all our experiments, we use the Vivado Design Suite ver. 2019.1, RapidWright ver. 2019.1, and Xilinx Virtex-7 FPGA VC707 Evaluation Kit. We do not perform the experiments on a cloud FPGA because we need to access the embedded temperature sensor to measure the impact of PVT variations on the proposed metric. We use virtual IOs and logic analyzer (ILA) to instrument the design, simulate the shell, trigger the sensors, and retrieve their outputs. The virtual IOs and the ILA are instantiated as IP cores inside the shell. We repeat all the experiments ten times. In all of them, the sensor sampling period is 1.28 \( \mu \)s, and the transient window size \( L \) is ten samples. The clock frequency is set to 200 MHz.

![Graph showing PVT variability results](image)

Fig. 5. PVT variability results: The difference in the frequency of RO-based sensor from variation in the manufacturing process, temperature, and steady-state or transient voltage fluctuations.

A. PVT Variability

To quantify the impact of PVT variations on the sensor output under controlled conditions, we perform a set of experiments and report the mean and standard deviation of all measured sensor frequency changes in Fig. 5.

In the process variation experiment, we place 1320 sensors (approx. one in the center of every 5 \( \times \) 5 square of CLBs) in the role space of an idle FPGA, read their frequencies and report the absolute frequency difference between every pair of these spatially-distributed sensors.

We investigate two aspects of the temperature change. First, we place a single sensor in the center of each CR and let them run for 15 minutes and monitor the FPGA temperature (using the embedded on-chip temperature sensor) to see if their switching activity causes any heating. Our results show no consistent temperature increase and the average temperature change of 1.03°C. Then, we place a self-heating circuit consisting of 12,500 instances of three-stage ROs, similar to Tian et al. [48], and four of our sensors near the FPGA temperature sensor. We let the self-heater run for 15 minutes; this, on average, results in a temperature increase of 18°C. We read the sensor outputs before enabling the self-heater and also one millisecond after disabling it. Assuming a linear relationship between the FPGA temperature and RO frequencies [49], we can infer that a one-degree increase in the temperature can, on average, result in 0.06 MHz of frequency drop, which is less than 0.1% of the idle sensor frequency (Table I).

We investigate two types of voltage fluctuations: steady-state and transient. In both experiments, we use a synthetic workload, similar to Gnad et al. [25]: an array of flip-flops whose outputs are connected to their inputs through an inverter and toggle at the clock frequency of 200 MHz. We place this workload evenly in the CRs of the role regions to produce an equal amount of steady-state or transient voltage fluctuation.
for the spatially-distributed sensors. For the steady-state voltage experiment, we configure 1.8% of all the flip-flops (as a realistic amount of toggling flip-flops of a circuit [25]); for the transient, we increase this number to 6% (a number sufficient for causing timing faults in a colocated 128-bit ripple-carry adder). In the steady-state voltage experiment, we let the workload run for 15 minutes and read the sensor outputs once while the workload is running and once one millisecond after the workload deactivation. We report the mean and standard deviation of the difference in sensor frequencies between these two points. In the transient voltage fluctuation experiment, we let the sensors run alone for 15 minutes, read their outputs, and then suddenly enable all the toggling flip-flops; the worst-case frequency drop caused by the transient voltage fluctuation is then reported.

Fig. 5 shows the impact of PVT variations on the sensor frequency. As expected, the impact of temperature on our compact LUT-based sensors is minimal. The impact of the steady-state voltage fluctuation follows closely. The transient voltage fluctuations have the highest impact on the sensor frequencies, although the variation of this impact across all the sensors is low. This low variability of the sensor response to the steady-state voltage fluctuations and the transient voltage fluctuations means that the coefficient $k$ in Eq. (2) is relatively constant across different sensor locations. In contrast, looking at the results of the process variation experiment, we see high variation in the sensor frequencies. Given that the coefficient $k$ is relatively constant, the source of the variability observed in the process variation experiment lies primarily in the offset $f_O$ in Eq. (2). Hence the need for a metric that is not affected by the offset $f_O$.

B. Monitoring Voltage Fluctuations to Locate Attacker

In this section, we present a proof-of-concept implementation of our monitoring system in a virtualized FPGA setting with four roles. Each role may contain two types of circuits: power-hungry (H) and power-wasting (W).

1) Circuits Under Monitoring: We embed the sensors into five setups, each containing at least one power-waster and one (or more) legitimate power-hungry circuits. We test two power-waster circuits. The first, $W_1$, is 70,000 instances of an asynchronous single-stage ring oscillator (Fig. 2a). The second power-waster, $W_2$, is 24,000 instances of a synchronous power-wasting circuit (Fig. 2b). With $W_2$, we successfully perform the timing-fault attack on a 128-bit ripple-carry adder [11], [29]. To observe the timing faults, we colocate $W_2$ with a 64-bit and a 128-bit ripple-carry adder. Both adders repeatedly perform two types of operations to propagate the carry through the worst-case-delay path: adding 1 to -1 and subtracting 1 from 0 in two’s complement. Similar to the approach of Krautter et al. [11], we use the 64-bit adder as the golden model, showing the correct output of the operations, and we use the 128-bit adder as the circuit under attack. We compare their 64 most significant bits to detect a timing failure in the 128-bit adder.

As power-hungry circuits, we choose a real image processing application, $H_1$, and a synthetic noise generator, $H_2$. Beside DSP slices and logic, $H_1$ makes an extensive use of DDR memory, MicroBlaze, AXI4 interfaces and AXI GPIOs. $H_2$ is inspired by the implementation of a noise generator circuit by Giechaskiel et al. [37]: 1,000 instances of a 32-bit linear feedback shift registers (LFSRs), where each two are paired with a 32-bit counter. We enable two of these LFSRs with an initial seed and then add their outputs to generate the seed for the next two paired LFSR; this pattern is repeated.

2) Locating Attacker: To demonstrate the locating functionality, we embed the sensors into five experimental setups listed in Table II. Fig. 6 illustrates the floorplan of each setup; all setups follow the role placement in Fig. 1. As $W_2$ requires more resources than what is available in a single role region, we assign two role regions to $W_2$ (Table II). In all the experiments, we monitor the FPGA voltage for a period of 655.36 µs (512 sensor samples). To simulate a continuous measurement in which we do not know when an attack occurs, we let the system run for 163.84 µs before enabling the attacker. Fig. 7 reports the sensors outputs in terms of $\Delta \tilde{f}$ over time for the setup with $W_2$, $H_1$, and $H_2$ (setup e in Table II and Fig. 6e). This figure shows that before activating the attacker, all $\Delta \tilde{f}$ are almost zero, suggesting no significant transient voltage fluctuations. During the attack, all $\Delta \tilde{f}$ drop by more than 60 MHz. Therefore, the change in $\Delta \tilde{f}$ can signal the sudden transient voltage drop and can be used as a trigger for the location analysis. The inset of Fig. 7 focuses on the transient sliding windows that cover the first 10 µs of the attack, which is when the highest transient voltage drop occurs (sample 130 to 139). The outputs of these windows show that, while all the sensors are affected by the transient voltage drop, the sensors that are inside the CRs with the power-wasting circuit have the highest $\Delta \tilde{f}$ (CRs 6, 7, 9, and 11 in Fig. 7). After the attack, the FPGA experiences a voltage overshoot as it takes time for the PDN to decrease the supplied voltage in response to the deactivation of the attacker; hence, $\Delta \tilde{f}$ changes the polarity. After this recovery period, all $\Delta \tilde{f}$ converge back to zero.

To locate the user with power-wasting activity, we use a weighted score analysis of the $\Delta \tilde{f}$ measurements. To locate the attacker in a setup with $N$ occupied CRs and multiple roles, we first identify the $N$ corresponding sensors. Then, we create a list $S = \{s_0, s_1, \ldots, s_i, \ldots, s_{N-1}\}$, $(s_i \neq s_j \forall (i \neq j) \in \{0, 1, \ldots, N - 1\})$, where $s_0$ has the lowest $\Delta \tilde{f}$ and $s_{N-1}$ has

<table>
<thead>
<tr>
<th>Setup</th>
<th>Circuits</th>
<th>Role region 1</th>
<th>Role region 2</th>
<th>Role region 3</th>
<th>Role region 4</th>
</tr>
</thead>
<tbody>
<tr>
<td>a</td>
<td>$W_1$ &amp; $H_1$</td>
<td>$H_2$</td>
<td>-</td>
<td>$W_1$</td>
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<td>b</td>
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<td>$W_2$</td>
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<tr>
<td>d</td>
<td>$W_2$ &amp; $H_2$</td>
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In Eq. (6), variable \( I_U \) is set to one for user \( U \), if sensor \( s_i \) is inside their role region; otherwise, it is zero. Fig. 8 shows the user score averaged across ten runs for all the setups in Fig. 6. In all the runs, the score of the power-wasting user is considerably higher than the score of the power-hungry user (2.21–7.40× higher), which shows, as expected, that the majority of the sensors with low \( \Delta \tilde{f} \) are inside the attacker.

VII. CONCLUSION

With the capacity of the high-end FPGAs increasing, the current single-user per FPGA usage model will soon be replaced with multi-tenant virtualized FPGAs vulnerable to voltage attacks. To resolve this vulnerability, we intercept the standard design flow after the role is placed and routed to insert a nonintrusive adaptive network of spatially-distributed on-chip voltage sensors into the role. We propose a metric that is minimally affected by process variations and a novel measurement technique for sensing transient voltage drops. We are the first to use a synchronous power-wasting circuit, capable of performing timing faults, on 7-series Xilinx FPGAs, and successfully locate it. Our technique can be easily customized to other FPGA families and virtualized FPGA partitioning schemes. Our monitoring system allows the multi-tenant virtualized FPGAs to use spatially-distributed on-chip voltage sensors with no overhead in terms of user space to locate power-wasting circuits and take preventive measures. Future work will integrate our monitoring system into an open-source shell and add elastic sensing and real time decision making.

REFERENCES


1The lower the \( \Delta \tilde{f} \), the higher the transient voltage drop.


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